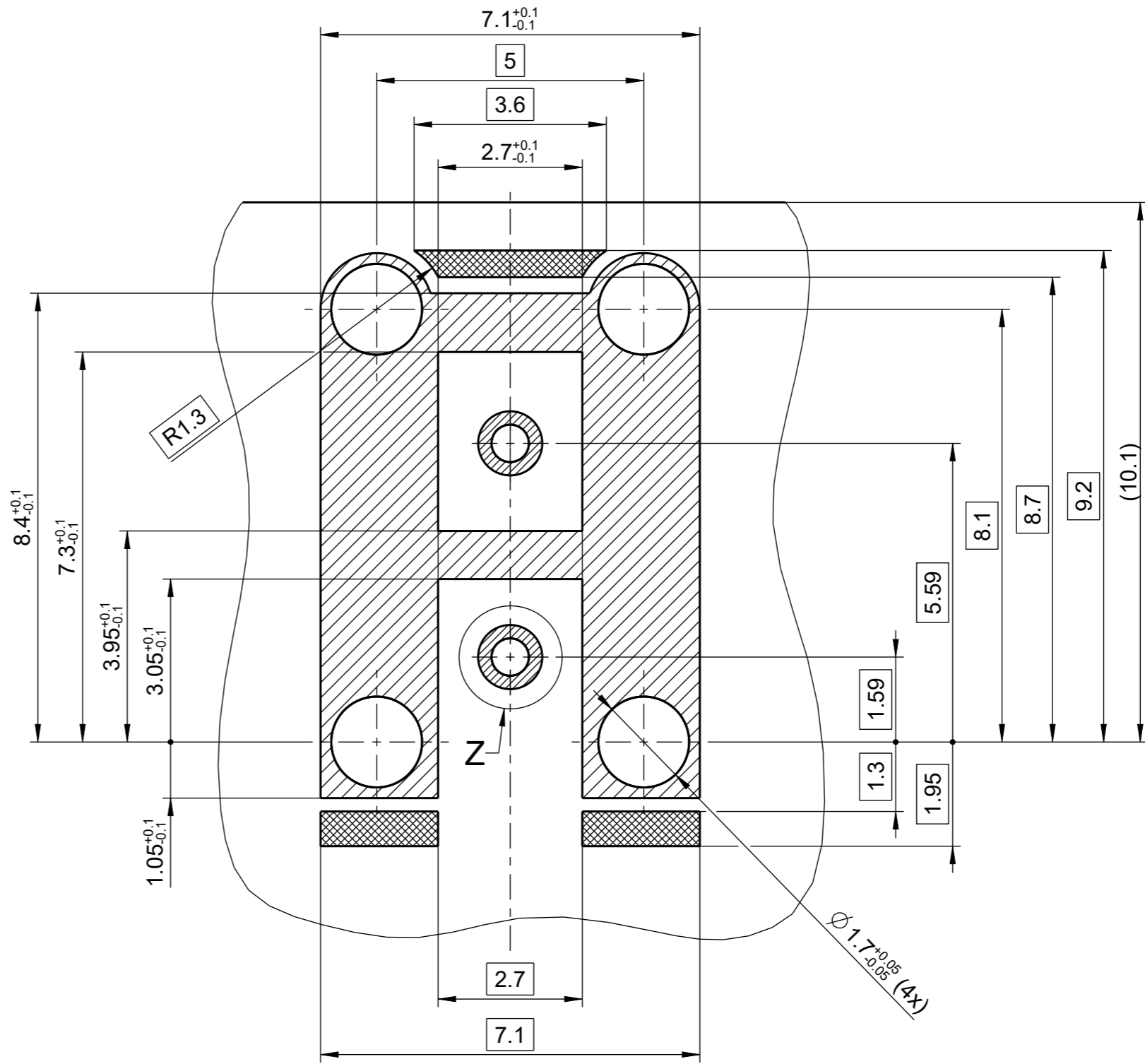
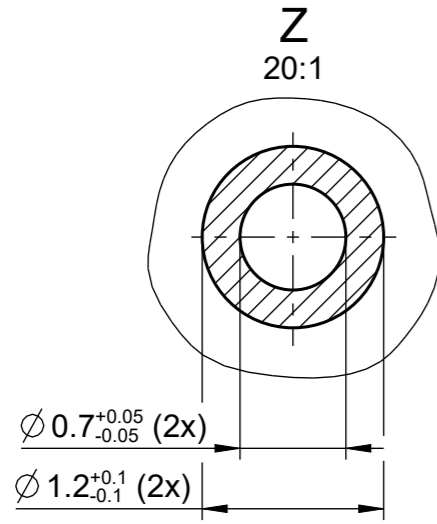


- 1) Alle Bohrungen durchkontaktieren mit Restringen auf Rückseite.
 (Restringbreite min. 0.2mm)
*All drill holes plated inclusive pads on the backside.
 (padwidth min. 0.2mm)*
- 2) Lötpastenhöhe 0.1 mm min.
Thickness of soldering paste 0.1 mm min.



- Lötfläche / solder area 6x
- Auflagefläche, frei von Lot / stand off area, free of solder 5x

Die angegebenen Maße und Toleranzen sind nur Empfehlungen
The stated dimension are only recommendations

A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

6x alle Bohrungen / all drill holes $\varnothing 0.05$ M CZ A

Rosenberger				general tolerance		scale: 10:1	weight[g]: ---
				ISO 2768 mH	RN 006-01	surface[mm ²]: ---	
vertraulich / confidential				date	name	title: PCB Layout PCB layout	
				drawn	12.02.2019		
check	24.03.2022	B_Krammer					
appr.	24.03.2022	T_Georg	drawing-no.: MB_793		sheet: 1		
a00	22-s069	G_Lisowski	17.03.2022	dimensioning incl. plating		of: 1	
300	20-2139	M_Jacobs	02.11.2020	Size ISO 14405 (E)		remarks: .	
200	20-0637	M2_Mamou	16.06.2020	Tolerancing ISO 8015			
100	19-v139	C_Zwinger	12.02.2019				
rev.	change-no	name	date				